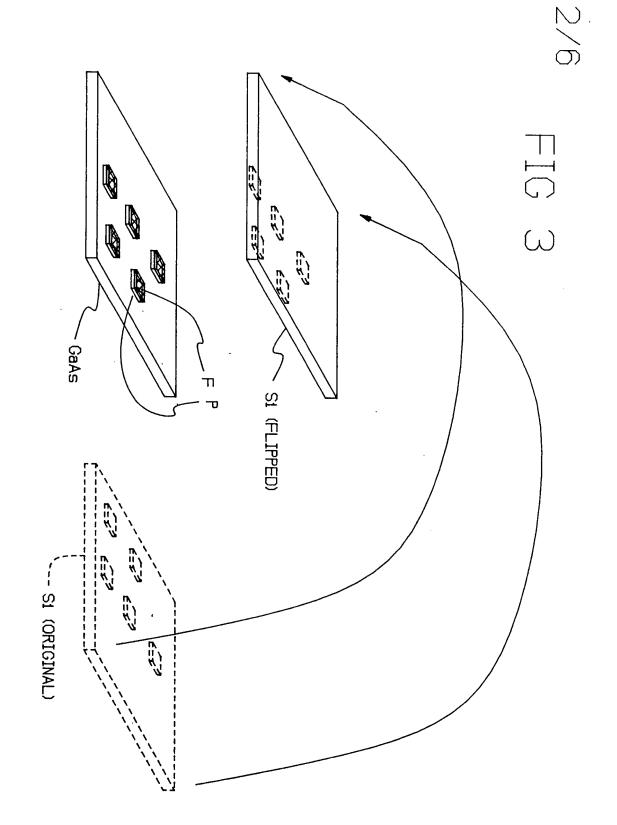
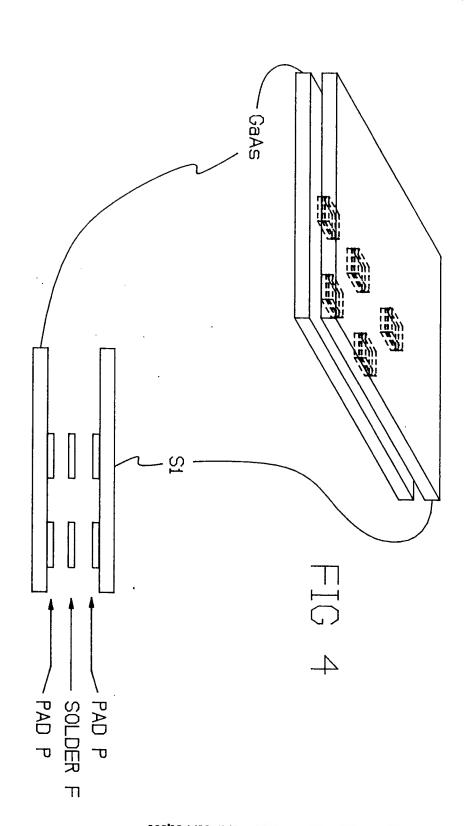
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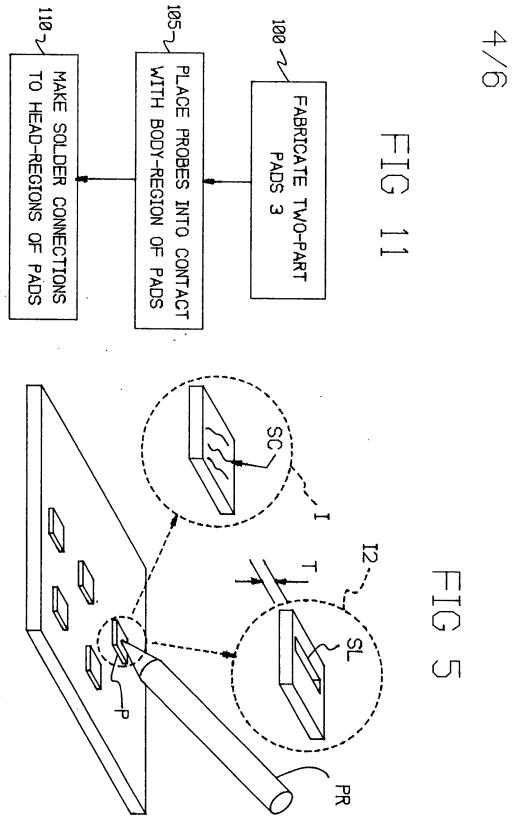
## BONDING PAD FOR FLIP-CHIP FABRICATION - GOOSSEN $\bf 8$ KRISHNAMOORTHY ATTY - G WELTE (765) 296 - 4699 S/N 09/761,886



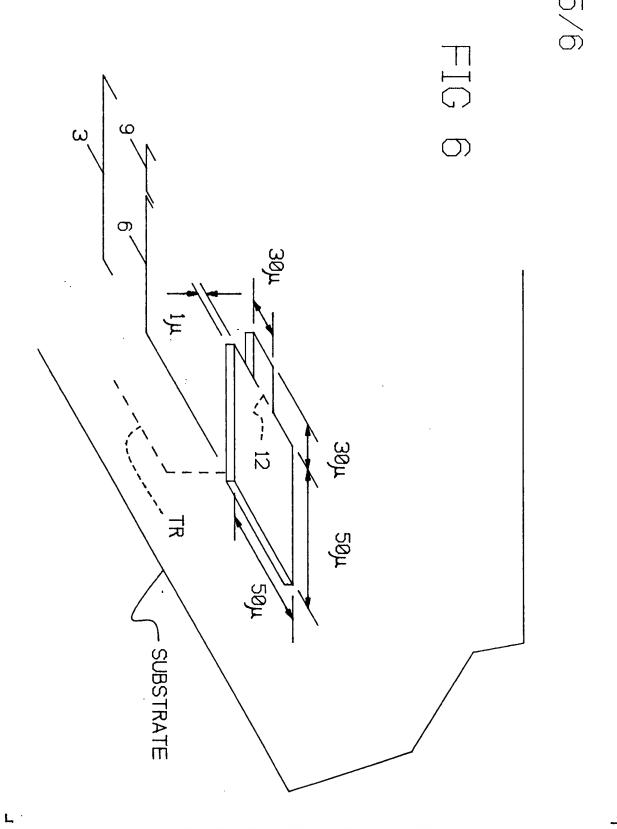
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PR BONDING PAD FOR FLIP-CHTP FABRICATION - GOOSSEN 8 KRISHNAMOORTHY ATTY - G WELTE (765) 296 - 4699 S/N 09/761,886

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